

B2
~~urging the first substrate and the electronic device towards one another so that the flexible contact elements make contact with the electronic component.~~

Sub B3
30. ~~(Added) A method according to claim 29, wherein the electronic device is a semiconductor wafer.~~

A1
31. (Added) A method according to claim 30, wherein the area is a plurality of integrated circuits on the semiconductor wafer; and the flexible contacts make contact with the plurality of die sites all at once.

Sub B3
32. ~~(Added) A method according to claim 29, wherein the area of the electronic device is a portion of an overall surface area of the electronic device.~~

Sub B3
33. ~~(Added) A method according to claim 29, wherein the electronic device is a printed circuit board.~~

Sub B3
34. ~~(Added) A method according to claim 29, wherein the electronic device is a packaging substrate.~~

35. (Added) A method according to claim 29, wherein the flexible elements are probe elements.

Sub B7
36. ~~(Added) A method according to claim 29, wherein the flexible elements further includes a protuberance at an end thereof.~~

Sub B8
37. ~~(Added) A method according to claim 29, wherein the flexible elements are shaped wires disposed on the surface of the second substrate.~~

Sub
B9
38. (Added) A method according to claim 29, wherein there are electrical connections between the second substrates and the first substrate.

Sub
B10
39. (Added) A method according to claim 29, wherein the first substrate is a space transformer.

Sub
B11
40. (Added) A method according to claim 29, wherein the electronic device is a semiconductor wafer; and the flexible contact elements of the second substrate contact individual semiconductor dies on the semiconductor wafer.

Sub
B12
41. (Added) A method according to claim 29, wherein the electronic device is a semiconductor wafer; and the flexible contact elements of the second substrate contacts at least one integrated circuit on the semiconductor wafer.

Sub
B13
42. (Added) A method according to claim 29, wherein the second substrate is aligned to the large substrate by a socket.

Sub
B14
43. (Added) A method according to claim 29, wherein the first substrate with the second mounted thereto is mounted to an electrical testing apparatus.

Sub
B15
44. (Added) A method according to claim 29, wherein the first substrate with the second mounted thereto is mounted to an electrical testing apparatus by a plurality of electrical connections.

Sub
B16
45. (Added) A probe card assembly comprising:

a probe card;

B16
a plurality of probe elements;

AA
a space transformer substrate having a top surface, a bottom surface, a first plurality of terminals disposed on the top surface, and a second plurality of terminals disposed on the bottom surface;

at least one second substrate having a top surface, a bottom surface;

means for effecting electrical connections between the at least one second substrate and the space transformer substrate; and

a plurality of probe elements disposed on the top surface of the at least one first substrate.

46. (Added) A probe card assembly, according to claim 45, wherein the probe elements are free-standing flexible conductors.

Sub B17
47. (Added) A probe card assembly, according to claim 46, wherein tip structures mounted to ends of the plurality of free-standing flexible conductors.

Sub B18
48. (Added) A probe card assembly, according to claim 46, characterized in that: the free-standing flexible conductor further indicates a protuberance at an end thereof.

Sub B19
49. (Added) A first substrate adapted in use to be mounted as a substrate tiles to a second substrate, comprising:

the first substrate having two opposite surfaces;

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~~flexible contacts extending from one of the two surfaces;~~

~~terminals on an other of the two opposite surfaces; and~~

~~means, within the first substrate, for connecting the terminals to the contacts.~~

B20
~~50. (Added) A method according to claim 29, further including plurality of groups of said plurality of the flexible electrical contact elements.~~

Sub B21
~~51. (Added) A method according to claim 29 or 49, wherein there is a least one of said second substrates mounted to said first substrate.~~

Sub B22
~~52. (Added) A method according to claim (27 to 28 or 49) wherein there are a plurality of said second substrates mounted to said first substrate.~~

REMARKS

Support for the added claims is found throughout the specification, in particular in US Patent 5,371,654, col. 6, lines 39-57, which patent is incorporated by references as US Application Serial Number 07/963,364 on page 8. Also, Fig. 3 shows an example of an embodiment where substrate 54 is electrically coupled to substrate 68 by interposer 76. A